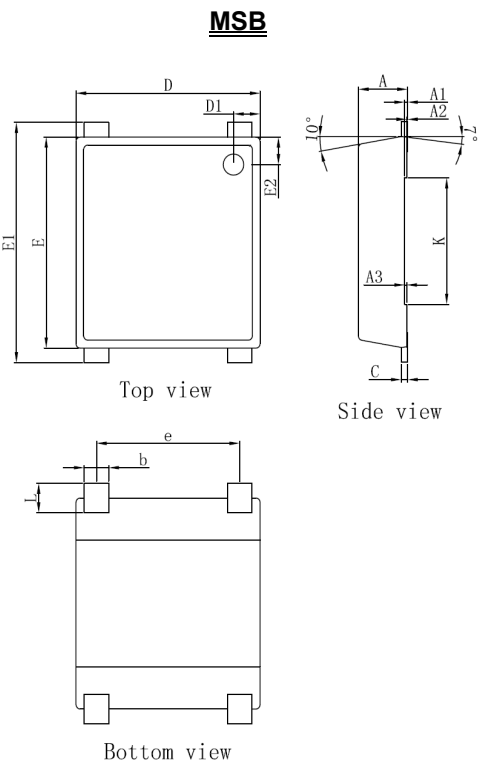


Package Dimension :



MSB			
Dim.	Min.	Typ.	Max.
A	1.10	1.20	1.30
A1	0.05	---	0.08
A2	0.00	0.02	0.05
A3	0.03	0.05	0.08
C	0.12	0.15	0.18
D	4.40	4.5	4.60
D1	0.60	0.65	0.70
E	4.90	5.00	5.10
E1	5.80	5.90	6.10
E2	0.60	0.65	0.70
L	0.70	0.80	1.00
b	0.55	0.60	0.70
e	3.45	3.50	3.55
K	2.95	3.00	3.05
All dimensions in millimeter			

FIG.1-FORWARD CURRENT DERATING CURVE

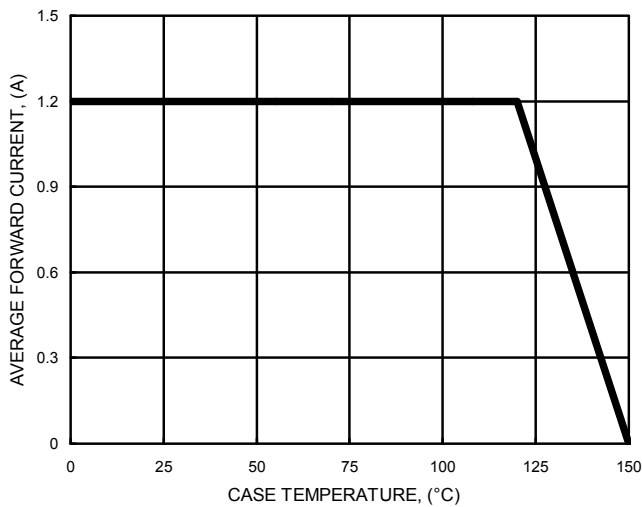


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

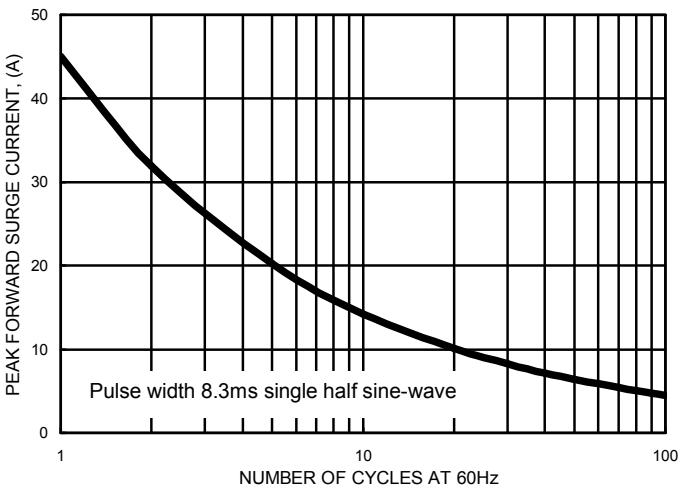


FIG.3- TYPICAL FORWARD CHARACTERISTICS

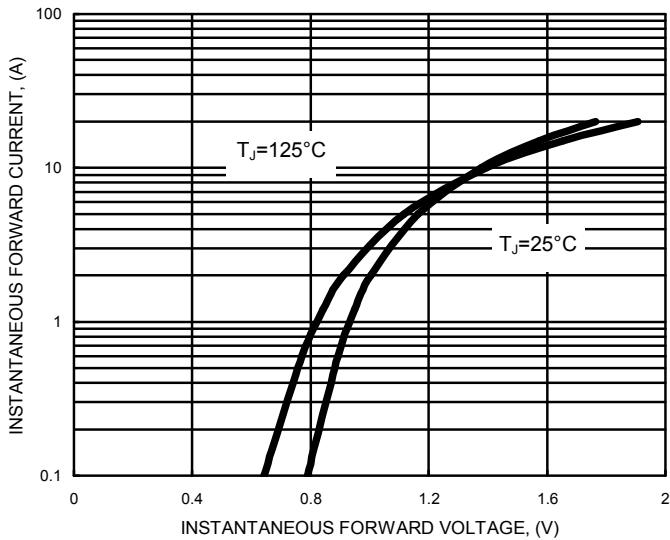


FIG.4- TYPICAL JUNCTION CAPACITANCE

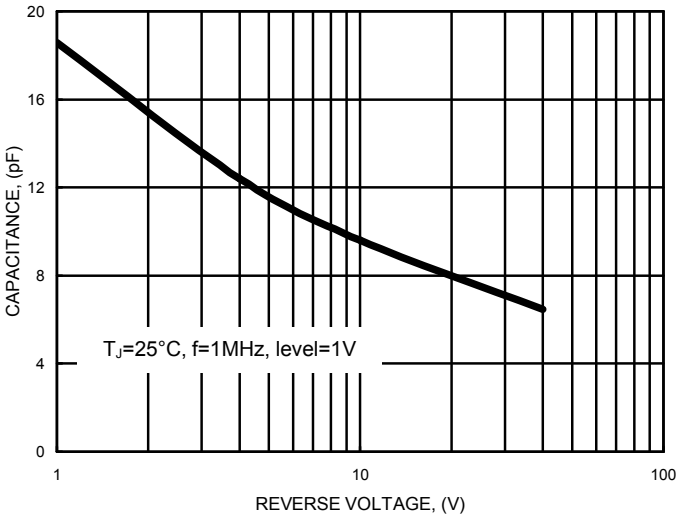
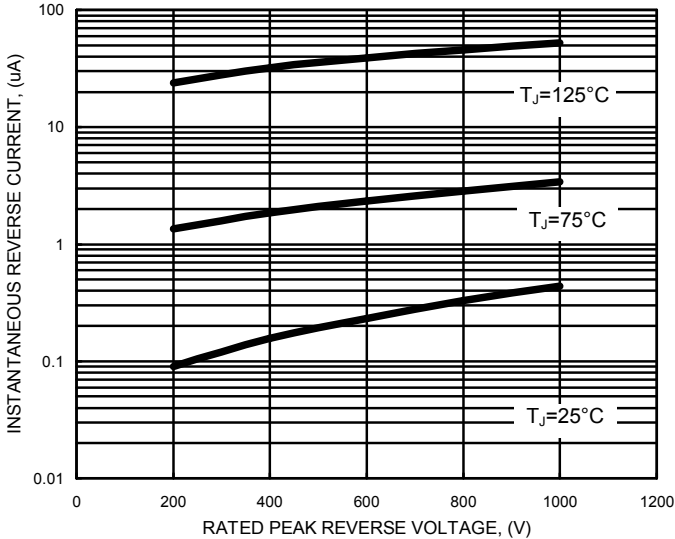
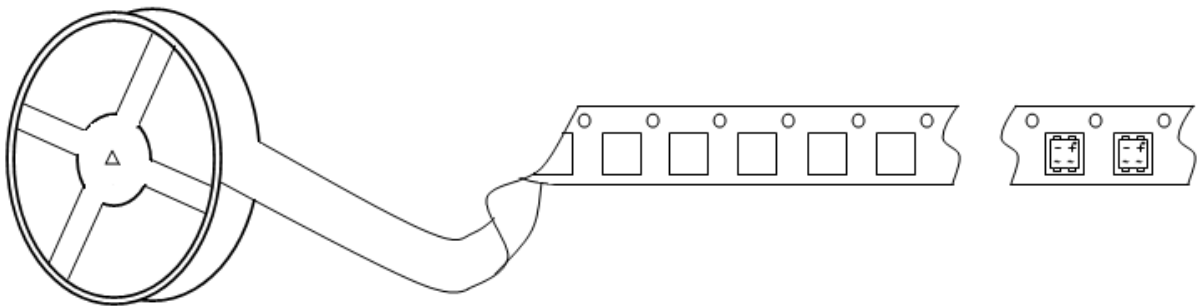


FIG.5- TYPICAL REVERSE CHARACTERISTICS

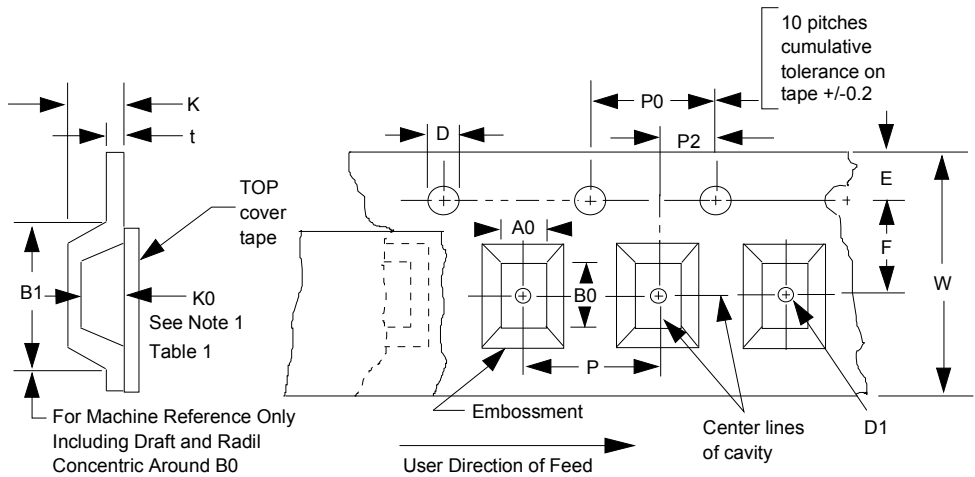


Packaging Information :

DEVICE	Q'TY/REEL (PCS)	REEL DIA. (mm)	BOX SIZE (mm)	Q'TY/BOX (PCS)	CARTON SIZE (mm)	Q'TY/CARTON (PCS)	MOQ
MSB12M	3000	330	334x334x21	3000	365x365x355	36K	36K



Embossed Carrier Dimension :



UNIT: mm

TAPE SIZE	D	E	PO	t (MAX)	A0	B0	K0
12mm	1.55+0.10/-0.0	1.75+/-0.10	4.0+/-0.10	0.4	4.8+/-0.1	6.0+/-0.1	1.5+/-0.1
	B1 (MAX)	D1 (MIN)	F	K (MAX)	P2	W	P
	8.2	1.5	5.5+/-0.1	2.2	2.0+/-0.05	12.0+/-0.30	8.0+/-0.1

Typical IR Reflow Soldering Thermal Profile :

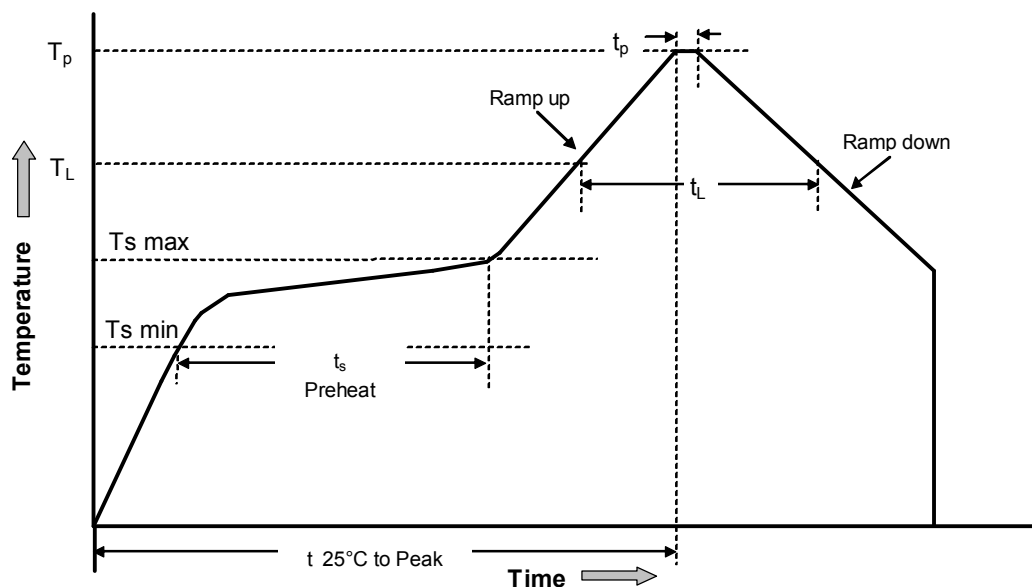


Table 1- Reflow profile

Reflow condition	Sn-Pb assembly	Pb-free assembly
Average ramp-up rate (Liquidus Temperature (TL) to Peak)	3 °C/second max.	3 °C/second max.
Preheat		
--Temperature Min, Ts (Min)	100 °C	150 °C
--Temperature Max, Ts (Max)	150 °C	200 °C
--Time (min to max, ts)	60-120 seconds	60-180 seconds
Ts(max) to TL		3 °C/second max.
- Ramp-up Rate		
Time maintained above:		
--Temperature(TL)	183 °C	217 °C
--Time(tL)	60-150 seconds	60-150 seconds
Peak Temperature (Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5 °C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature.	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface

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